



Material Content Data Sheet



Sales Product Name	TLE75008-EMD			Issued		28. September 2015		
MA#	MA001346130							
Package	PG-SSOP-24-9			Weight*		150.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.592	1.06	1.06	10575	10575
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		447	
	non noble metal	iron	7439-89-6	1.345	0.89		8937	
	non noble metal	copper	7440-50-8	54.617	36.29	37.23	362886	372382
wire	non noble metal	copper	7440-50-8	0.829	0.55	0.55	5507	5507
encapsulation	organic material	carbon black	1333-86-4	0.176	0.12		1172	
	plastics	epoxy resin	-	8.116	5.39		53924	
	inorganic material	silicondioxide	60676-86-0	79.924	53.10	58.61	531032	586128
leadfinish	non noble metal	tin	7440-31-5	2.947	1.96	1.96	19582	19582
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1557	1557
glue	plastics	epoxy resin	-	0.161	0.11		1067	
	noble metal	silver	7440-22-4	0.482	0.32	0.43	3202	4269
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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